DATA SHEET

TZA3033
SDH/SONET STM1/OC3 transimpedance amplifier

Product specification
Supersedes data of 2000 Sep 29

2002 Sep 06

Philips
Semiconductors

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SDH/SONET STM1/OC3 transimpedance amplifier

TZA3033

FEATURES

- Low equivalent input noise of 1 pA/√Hz (typical)
- Wide dynamic range from 0.25 μA to 1.6 mA (typical)
- Differential transimpedance of 44 kΩ
- Bandwidth typical 130 MHz
- Differential outputs
- On-chip Automatic Gain Control (AGC)
- No external components required
- Single supply voltage from 3.0 to 5.5 V
- Bias voltage for PIN diode
- Pin compatible with SA5223
- Goldplated version available for direct placement of photodiode on die.

APPLICATIONS

- Digital fibre optic receiver in short, medium and long haul optical telecommunications transmission systems or in high speed data networks
- Wideband RF gain block.

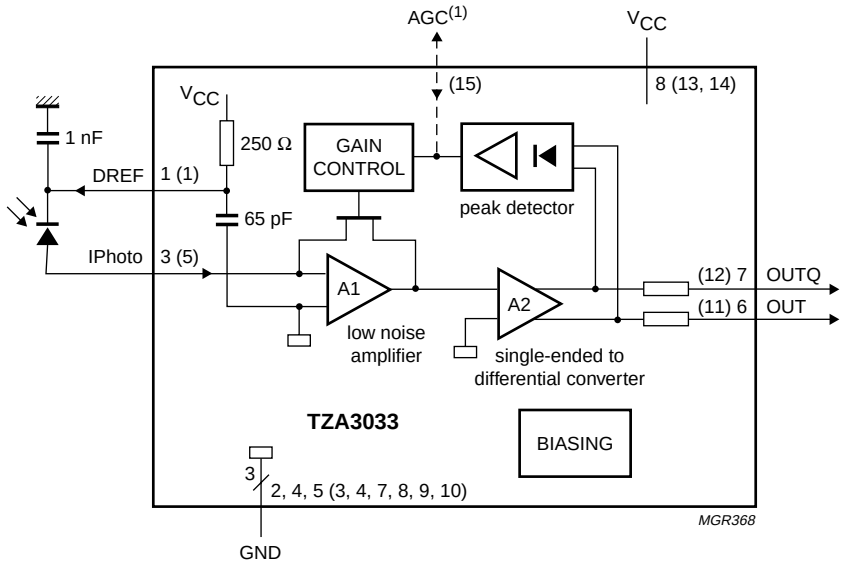
GENERAL DESCRIPTION

The TZA3033 is a low-noise transimpedance amplifier with AGC designed to be used in STM1/OC3 fibre optic links. It amplifies the current generated by a photo detector (PIN diode or avalanche photodiode) and converts it to a differential output voltage.

ORDERING INFORMATION

TYPE NUMBER	PACKAGE		
	NAME	DESCRIPTION	VERSION
TZA3033T	SO8	plastic small outline package; 8 leads; body width 3.9 mm	SOT96-1
TZA3033U	–	bare die in waffle pack carriers; die dimensions 1.030 × 1.300 mm	–
TZA3033U/G	–	bare die with goldplating in waffle pack carriers; die dimensions 1.030 × 1.300 mm	–

BLOCK DIAGRAM



The numbers in brackets refer to the pad numbers of the bare die version.

(1) AGC analog I/O is only available on the TZA3033U (pad 15).

Fig.1 Block diagram.

PINNING

SYMBOL	PIN TZA3033T	PAD TZA3033U	TYPE	DESCRIPTION
DREF	1	1	analog output	bias voltage for PIN diode; cathode should be connected to this pin; note 1
TESTA	–	2	–	for test purposes only; to be left open in application
GND	2	3, 4	ground	ground
IPhoto	3	5	analog input	current input; anode of PIN diode should be connected to this pin; DC bias voltage is 1048 mV
TESTB	–	6	–	for test purposes only; to be left open in application
GND	4	7, 8	ground	ground
GND	5	9, 10	ground	ground
OUT	6	11	output	data output; pin OUT goes HIGH when current flows into pin IPhoto
OUTQ	7	12	output	data output; compliment of pin OUT
V_{CC}	8	13, 14	supply	supply voltage
AGC	–	15	input/output	AGC analog I/O

Note

1. For the TZA3033U/G this pad is connected to the gold layer on top of the passivation layer.

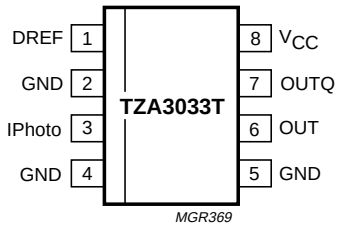


Fig.2 Pin configuration.

FUNCTIONAL DESCRIPTION

The TZA3033 is a transimpedance amplifier intended for use in fibre optic links for signal recovery in STM1/OC3 applications. It amplifies the current generated by a photo detector (PIN diode or avalanche photodiode) and transforms it into a differential output voltage. The most important characteristics of the TZA3033 are high receiver sensitivity and wide dynamic range.

High receiver sensitivity is achieved by minimizing noise in the transimpedance amplifier. The signal current generated by a PIN diode can vary between 0.25 μA to 1.6 mA (p-p). An AGC loop (see Fig.1) is implemented to make it possible to handle such a wide dynamic range. The AGC loop increases the dynamic range of the receiver by reducing the feedback resistance of the preamplifier.

The AGC loop hold capacitor is integrated on-chip, so an external capacitor is not needed for AGC. The AGC voltage can be monitored at pad 15 on the bare die (TZA3033U). Pad 15 is not bonded in the packaged device (TZA3033T). This pad can be left unconnected during normal operation. It can also be used to force an external AGC voltage. If pad 15 (AGC) is connected to V_{CC}, the internal AGC loop is disabled and the receiver gain is at a maximum. The maximum input current is then approximately 10 μA.

A differential amplifier converts the output of the preamplifier to a differential voltage (see Fig.3).

The logic level symbol definitions are shown in Fig.4.

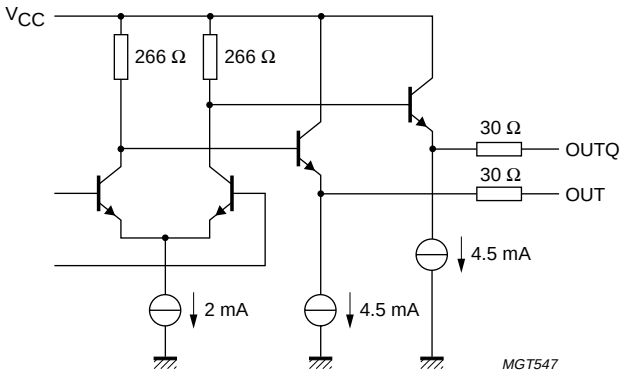


Fig.3 Data output circuit.

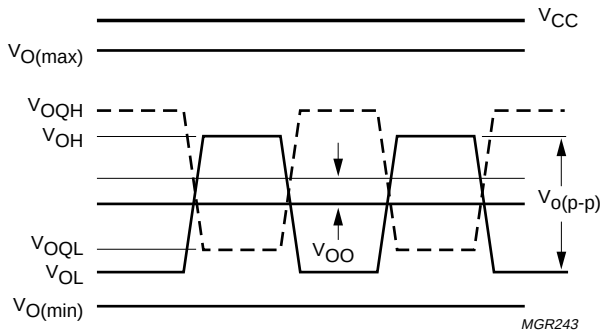


Fig.4 Logic level symbol definitions for data outputs OUT and OUTQ.

PIN diode bias voltage DREF

The transimpedance amplifier together with the PIN diode determine to a large extent the performance of an optical receiver. The key parameters of a transimpedance amplifier like sensitivity, bandwidth, and the Power Supply Rejection Ratio (PSSR), are especially influenced by how the PIN diode is connected to the input and the layout around the input pin. The total capacitance at the input pin is critical to obtain the highest sensitivity. It should be kept to a minimum by reducing the capacitor of the PIN diode and the parasitics around the input pin. The PIN diode should be placed very close to the IC to reduce the parasitics. Because the capacitance of the PIN diode depends on the reverse voltage across it, the reverse voltage should be selected as high as possible.

The PIN diode can be connected to the input as shown in Fig.5. In Fig.5 the PIN diode is connected between DREF and IPhoto. Pin DREF provides an easy bias voltage for the PIN diode. The voltage at DREF is derived from V_{CC} by a low-pass filter. The low-pass filter consisting of the internal resistor R1, the internal capacitor C1 and the external capacitor C2 rejects the supply voltage noise. The external capacitor C2 should be equal to or larger than 1 nF for a high PSRR.

It is preferable to connect the cathode of the PIN diode to a voltage higher than V_{CC} when such a voltage source is available on the board. In this case the DREF pin can be left unconnected.

The reverse voltage across the PIN diode is 3.95 V (5 – 1.05 V) for a 5 V supply and 2.25 V (3.3 – 1.05 V) for a 3.3 V supply.

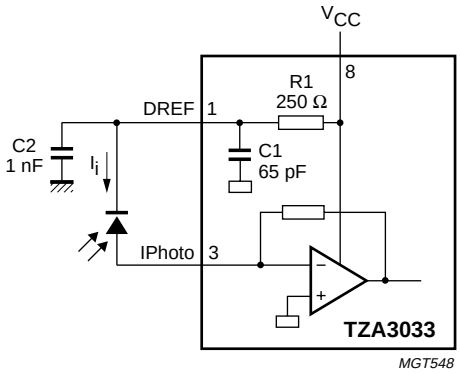


Fig.5 Connecting the PIN diode to the input.

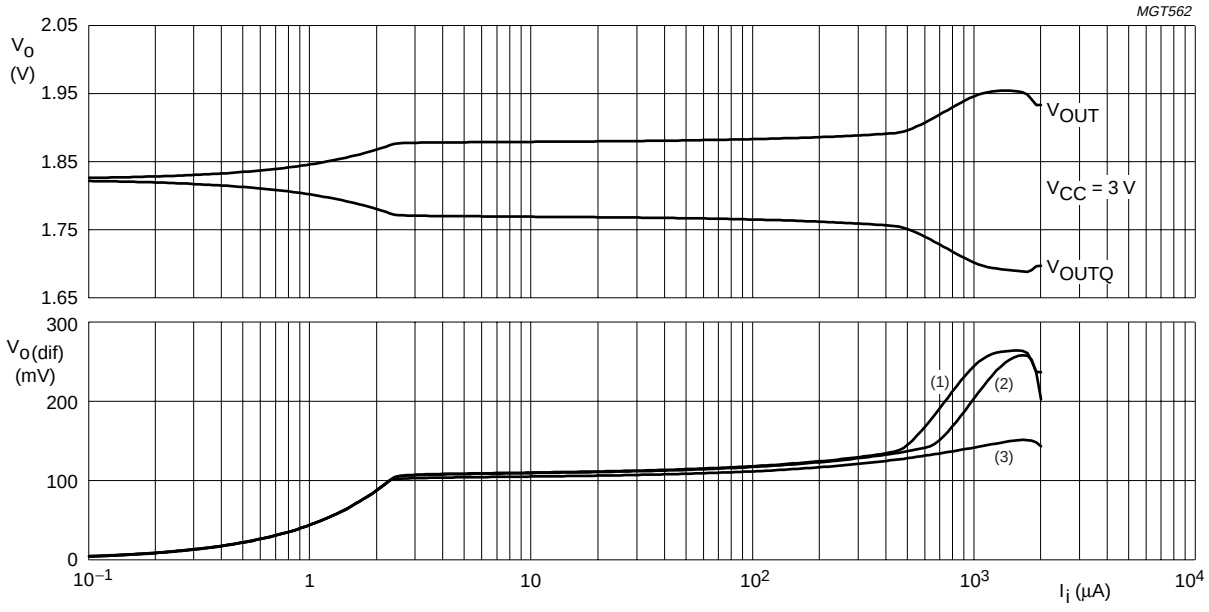
AGC

The TZA3033 transimpedance amplifier can handle input currents from 0.25 μA to 1.6 mA. This means a dynamic range of 79 dB. At low input currents, the transimpedance must be high to obtain an adequate output voltage, and the noise should be suitably low to guarantee minimum bit error rate. At high input currents however, the transimpedance should be low to avoid pulse width distortion. This means that the gain of the amplifier has to vary depending on the input signal level to handle such a wide dynamic range. This is achieved in the TZA3033 by implementing an Automatic Gain Control (AGC) loop.

The AGC loop consists of a peak detector, a hold capacitor and a gain control circuit. The peak amplitude of the signal is detected by the peak detector and stored on the hold capacitor. The voltage across the hold capacitor is compared to a threshold level. The threshold level is set at an input current of 2.5 μA (p-p). AGC becomes active only for input signals larger than the threshold level. It is disabled for smaller signals. The transimpedance is then at its maximum value (44 kΩ differential).

When the AGC is active, the feedback resistance of the transimpedance amplifier is reduced to keep the output voltage constant. The transimpedance is regulated from 44 kΩ at low currents (I < 2.5 μA) to 200 Ω at high currents (I < 500 μA). Above 500 μA the transimpedance is at its minimum and can not be reduced further but the front-end remains linear until input currents of 1.6 mA (p-p).

The upper graph of Fig.6 shows the output voltages V_{OUT} and V_{OUTQ} of the TZA3033 as a function of the DC input current for a supply voltage of 3 V. In the lower graph the difference between both output voltages, $V_{o(dif)}$, is shown for supply voltages of 3, 3.3 and 5 V. It can seen from the graph that the output changes linearly up to an input current of 2.5 μA where the AGC becomes active. From this point on, the AGC tries to keep the differential output voltage constant around 110 mV for medium range input currents (input currents < 200 μA). The AGC can not regulate for input currents above 500 μA, and the output voltage rises again with the input current.



(1) V_{CC} = 3.0 V.
(2) V_{CC} = 3.3 V.
(3) V_{CC} = 5.0 V.

Fig.6 AGC characteristics.

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	MIN.	MAX.	UNIT
V_{CC}	supply voltage	–0.5	+5.5	V
V_n	DC voltage			
	pin 3/pad 5: IPhoto	–0.5	+2	V
	pins 6 and 7/pads 11 and 12: OUT and OUTQ	–0.5	V_{CC} + 0.5	V
	pad 15: AGC (TZA3033U only)	–0.5	V_{CC} + 0.5	V
	pin 1/pad 1: DREF	–0.5	V_{CC} + 0.5	V
I_n	DC current			
	pin 3/pad 5: IPhoto	–1	+2.5	mA
	pins 6 and 7/pads 11 and 12: OUT and OUTQ	–15	+15	mA
	pad 15: AGC (TZA3033U only)	–0.2	+0.2	mA
	pin 1/pad 1: DREF	–2.5	+2.5	mA
P_{tot}	total power dissipation	–	300	mW
T_{stg}	storage temperature	–65	+150	°C
T_j	junction temperature	–	150	°C
T_{amb}	ambient temperature	–40	+85	°C

HANDLING

Precautions should be taken to avoid damage through electrostatic discharge. This is particularly important during assembly and handling of the bare die. Additional safety can be obtained by bonding the V_{CC} and GND pads first, the remaining pads may then be bonded to their external connections in any order.

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	VALUE	UNIT
$R_{th(j-s)}$	thermal resistance from junction to solder point	160	K/W

CHARACTERISTICS

For typical values T_{amb} = 25 °C and V_{CC} = 5 V; minimum and maximum values are valid over the entire ambient temperature range and process spread; all voltages are measured with respect to ground; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V_{CC}	supply voltage		3	5	5.5	V
I_{CC}	supply current	AC coupled; R_L = 50 Ω				
		V_{CC} = 5 V	20	38	60	mA
		V_{CC} = 3.3 V	20	35	50	mA
P_{tot}	total power dissipation	V_{CC} = 5 V	100	190	330	mW
		V_{CC} = 3.3 V	60	116	180	mW
T_j	junction temperature		–40	–	+125	°C
T_{amb}	ambient temperature		–40	+25	+85	°C
R_{tr}	small-signal transresistance of the receiver	AC coupled; measured differentially				
		R_L = ∞	42	90	112	kΩ
		R_L = 50 Ω	21	45	66	kΩ
$f_{-3dB(h)}$	high frequency –3 dB point	AC coupled; measured differentially; C_i = 0.7 pF; R_L = 50 Ω				
		T_j = 125 °C	90	130	–	MHz
		T_j = 100 °C	100	130	–	MHz
PSRR	power supply rejection ratio	measured differentially; note 1				
		f = 100 kHz to 10 MHz	–	0.5	–	µA/V
		f = 100 MHz	–	10	–	µA/V
Bias voltage: pin DREF						
R_{DREF}	resistance between pins DREF and V_{CC}	DC tested	210	245	290	Ω
Input: pin IPhoto						
$V_{bias(IPhoto)}$	input bias voltage on pin IPhoto		800	1050	1300	mV
$I_{i(IPhoto)(p-p)}$	input current on pin IPhoto (peak-to-peak value)	note 2				
		V_{CC} = 5 V	0	1	1800	µA
		V_{CC} = 3.3 V	0	1	1600	µA
R_i	small-signal input resistance	f_i = 1 MHz; input current < 0.5 µA	–	330	–	Ω
$I_{n(tot)}$	total integrated RMS noise current over bandwidth (referenced to input)	Δf = 90 MHz; note 3	–	16	–	nA

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Data outputs: OUT and OUTQ						
$V_{o(cm)}$	common mode output voltage	AC coupled; R_L = 50 Ω	V_{CC} – 1.34	V_{CC} – 1.15	V_{CC} – 0.96	V
$V_{o(se)(p-p)}$	single-ended output voltage (peak-to-peak value)	AC coupled; R_L = 50 Ω; input current = 100 $\mu A_{(p-p)}$	40	110	200	mV
V_{OO}	differential output offset voltage	V_{CC} = 5 V	–50	+55	+150	mV
		V_{CC} = 3.3 V	–50	+35	+100	mV
$R_{o(se)}$	single-ended output resistance	DC tested	36	44	57	Ω
t_r	rise time	20% to 80%	–	2.3	3.9	ns
t_f	fall time	80% to 20%	–	2.3	3.9	ns
Automatic gain control loop: pad AGC						
$I_{th(AGC)}$	AGC threshold current	referred to the peak input current; tested at 10 MHz	–	2.5	–	µA
$t_{att(AGC)}$	AGC attack time		–	5	–	µs
$t_{decay(AGC)}$	AGC decay time		–	10	–	ms

Notes

1. PSRR is defined as the ratio of the equivalent current change at the input (ΔI_{IPhoto}) to a change in supply voltage:

   $$PSRR = \frac{\Delta I_{IPhoto}}{\Delta V_{CC}}$$

   For example, a + 4 mV disturbance on V_{CC} at 10 MHz will typically add an extra 2 nA to the photodiode current. The external capacitor between DREF and GND has a large impact on PSRR. The specification is valid with an external capacitor of 1 nF. The PSSR is guaranteed by design.

2. The Pulse Width Distortion (PWD) is <5% over the whole input current range. The PWD is defined as:

   $PWD = \left(\frac{\text{pulse width}}{T} - 1\right) \times 100\%$ where T is the clock period. The PWD is measured differentially with PRBS pattern of 10^{-23}.

3. All $I_{n(tot)}$ measurements were made with an input capacitance of C_i = 1 pF. This was comprised of 0.5 pF for the photodiode itself, with 0.3 pF allowed for the printed-circuit board layout and 0.2 pF intrinsic to the package. Noise performance is measured differentially.

TYPICAL PERFORMANCE CHARACTERISTICS

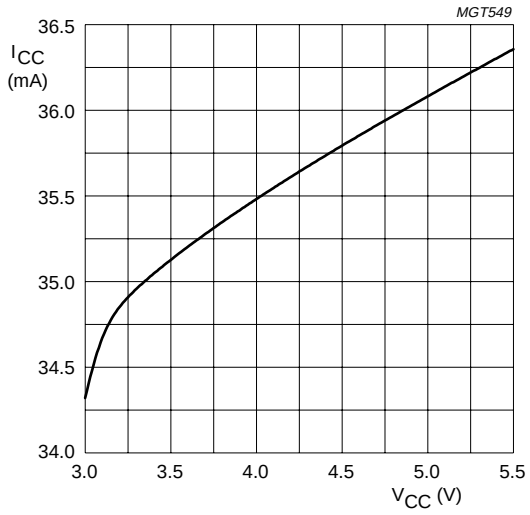
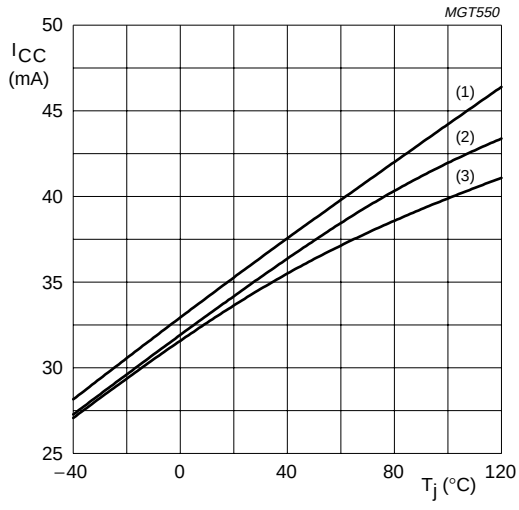


Fig.7 Supply current as a function of the supply voltage.



(1) V_{CC} = 5 V.
(2) V_{CC} = 3.3 V.
(3) V_{CC} = 3 V.

Fig.8 Supply current as a function of the junction temperature.

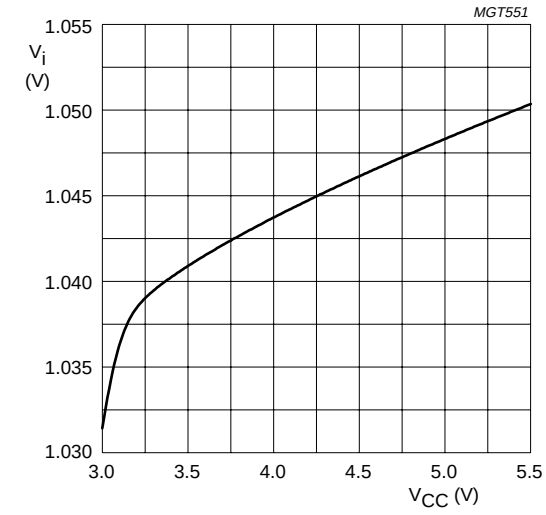
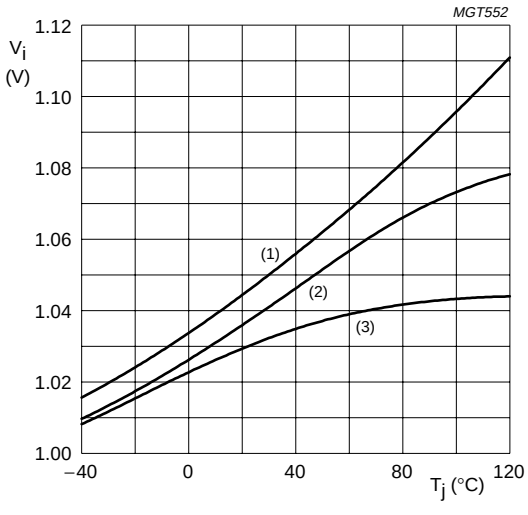
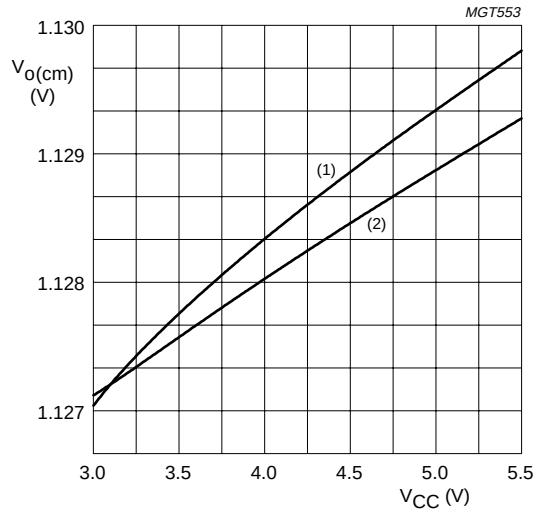


Fig.9 Input voltage as a function of the supply voltage.



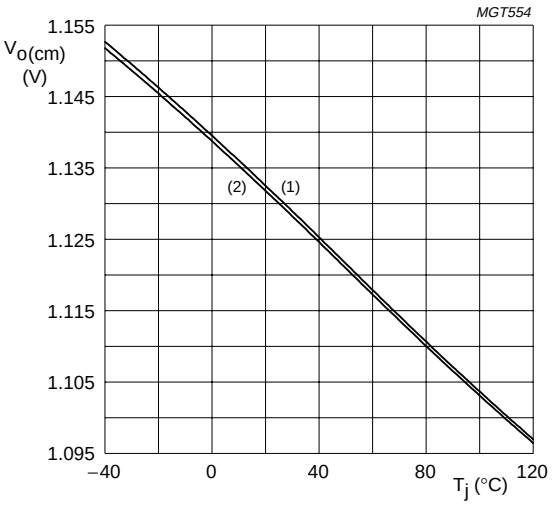
(1) V_{CC} = 5 V.
(2) V_{CC} = 3.3 V.
(3) V_{CC} = 3 V.

Fig.10 Input voltage as a function of the junction temperature.



(1) $V_{CC} - V_{OUT}$.
(2) $V_{CC} - V_{OUTQ}$.

Fig.11 Common mode voltage at the output as a function of supply voltage.



V_{CC} = 5 V.
(1) $V_{CC} - V_{OUT}$.
(2) $V_{CC} - V_{OUTQ}$.

Fig.12 The common mode voltage at the output as a function of the junction temperature.

APPLICATION INFORMATION

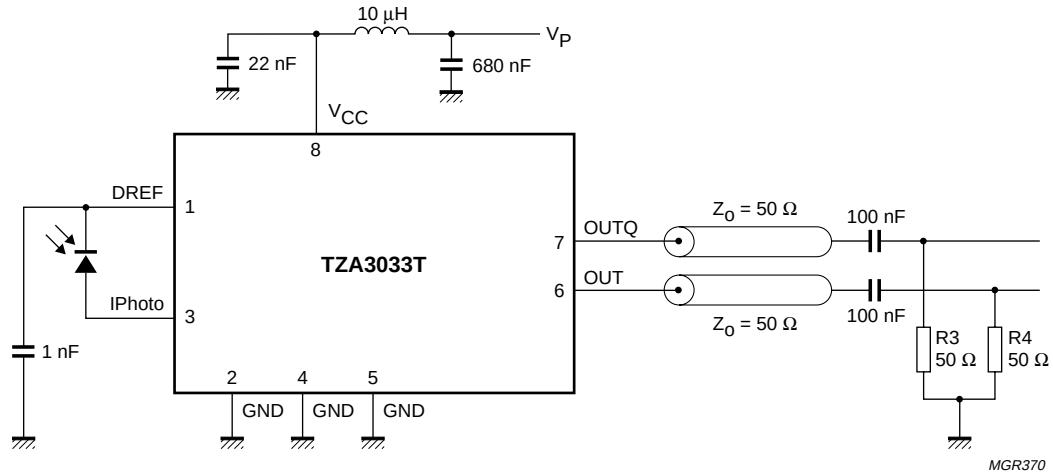


Fig.13 Application diagram.

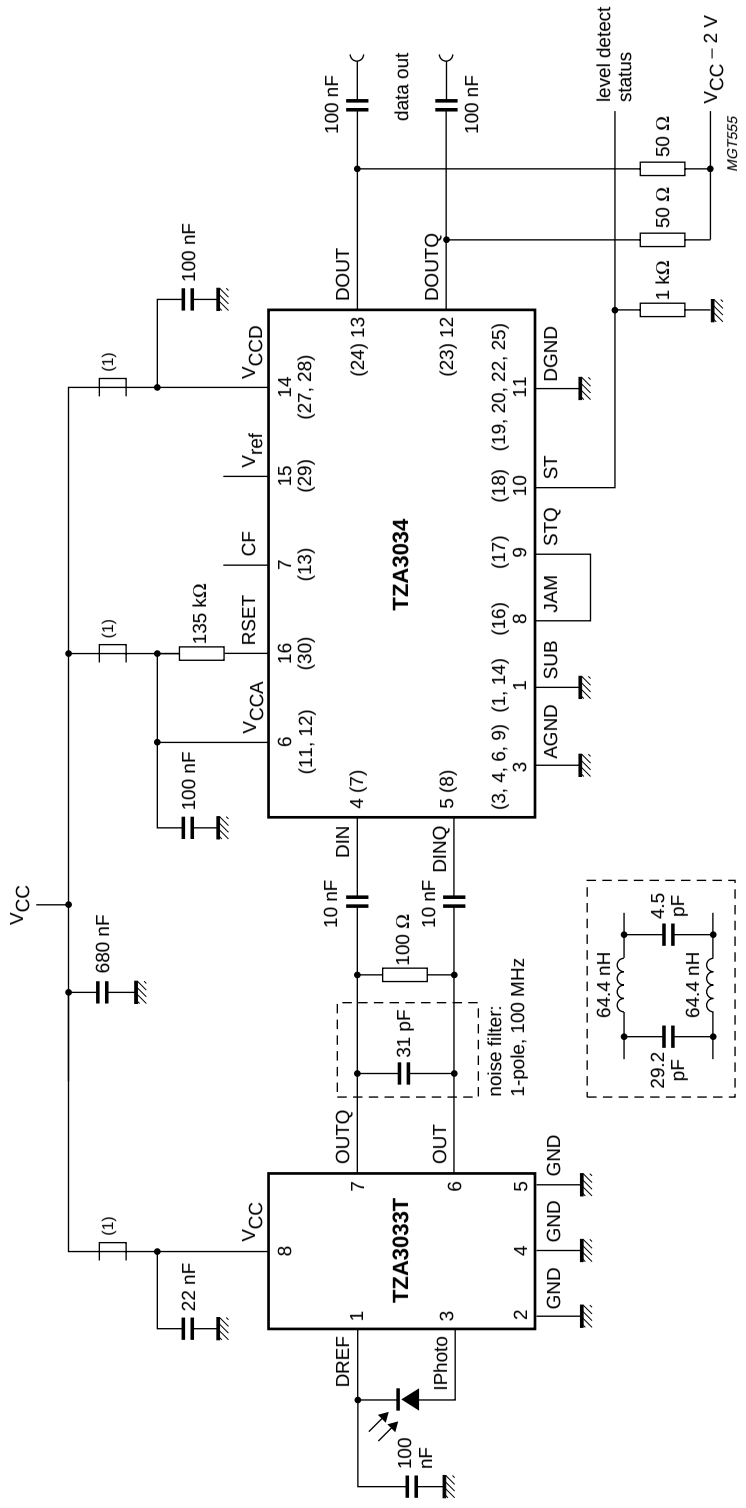
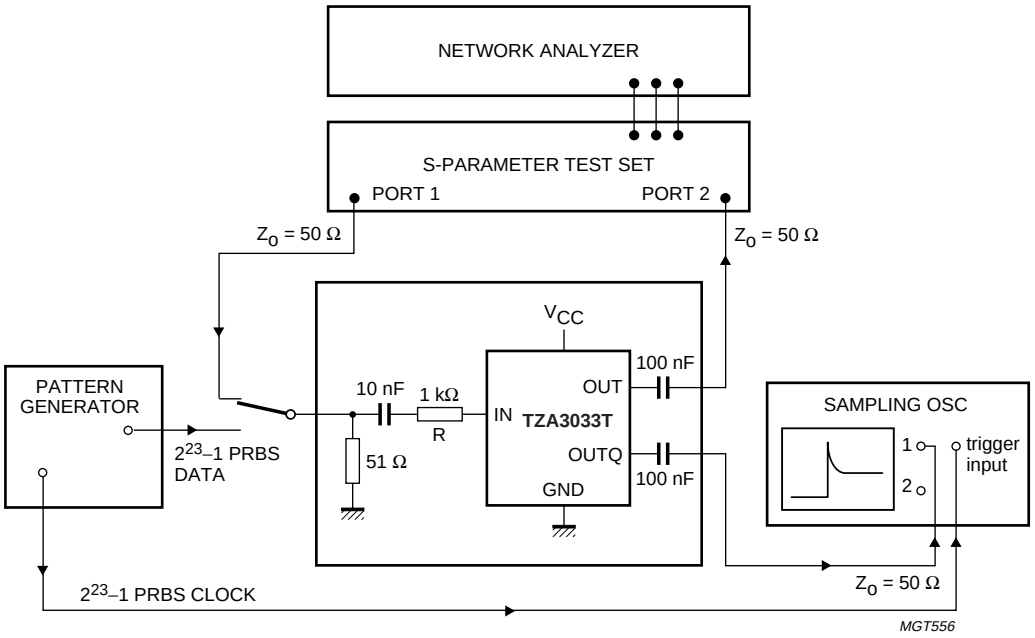


Fig.14 STM1/OC3 receiver using the TZA3033 and TZA3034.

Test circuits



Total impedance of the test circuit is Z_T and is calculated by the equation $Z_T = S_{21} \times (R + Z_{IN}) \times 2$ where S_{21} is the insertion loss of ports 1 and 2.

Typical values: R = 1 kΩ, Z_{IN} = 330 Ω.

Fig.15 Test circuit.

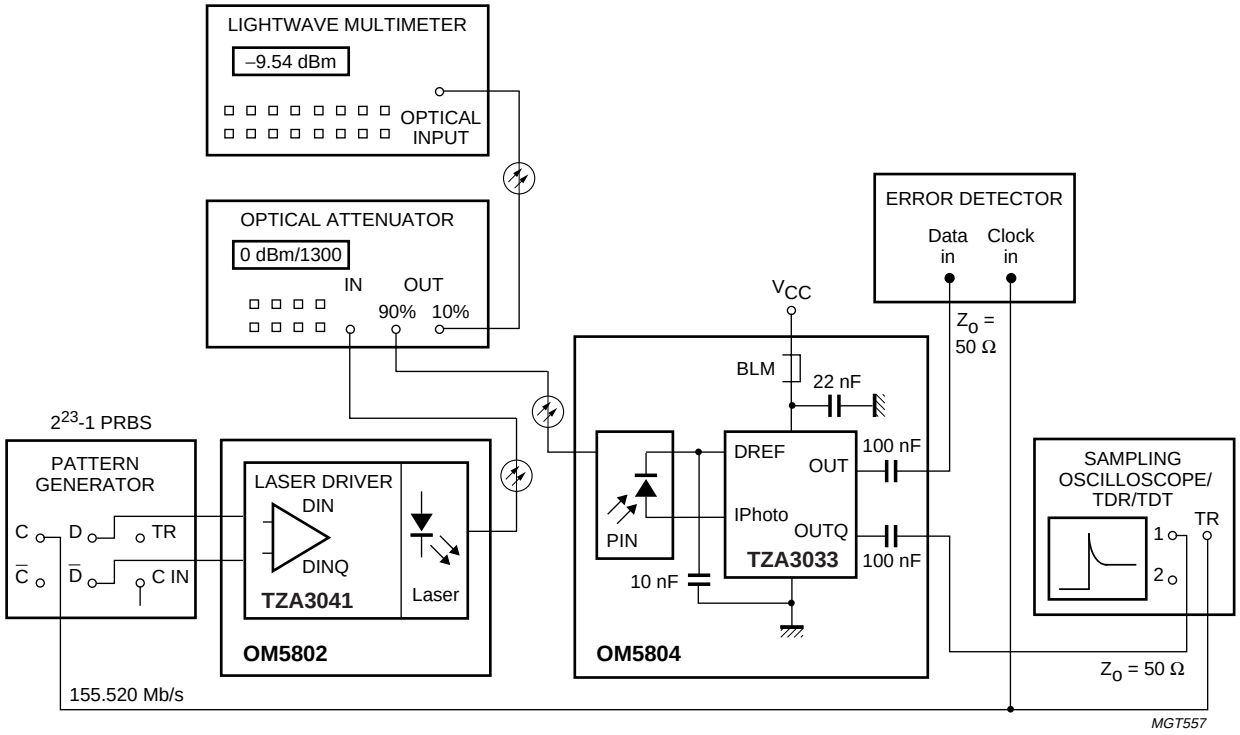


Fig.16 Optical test circuit.

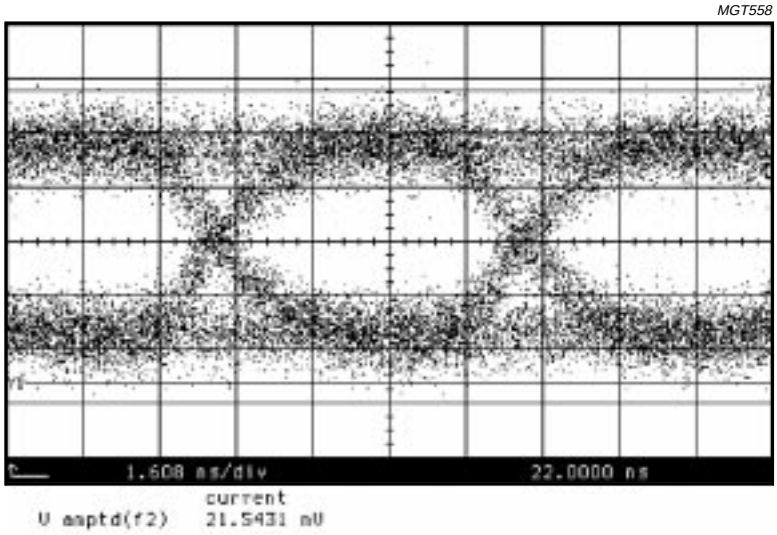


Fig.17 Differential output with −35 dBm optical input power [input current of 0.517 μA (p-p)].

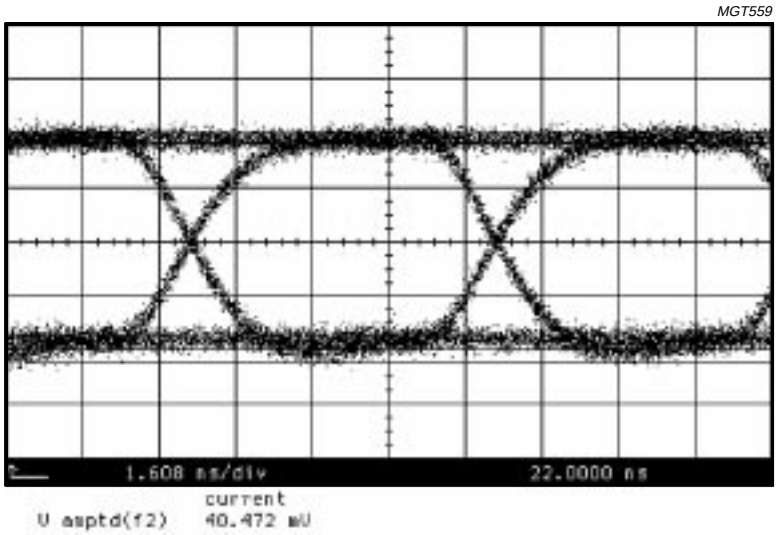


Fig.18 Differential output with −25 dBm optical input power [input current of 5.17 μA (p-p)].

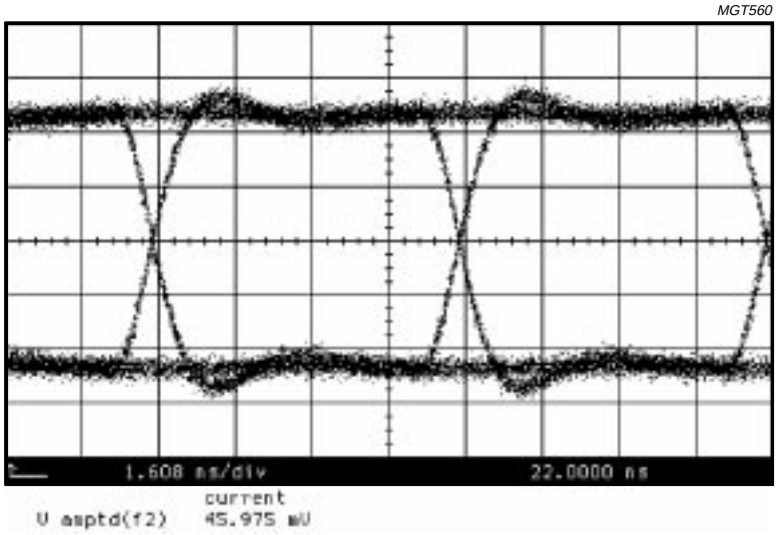


Fig.19 Differential output with −15 dBm optical input power [input current of 51.7 μA (p-p)].

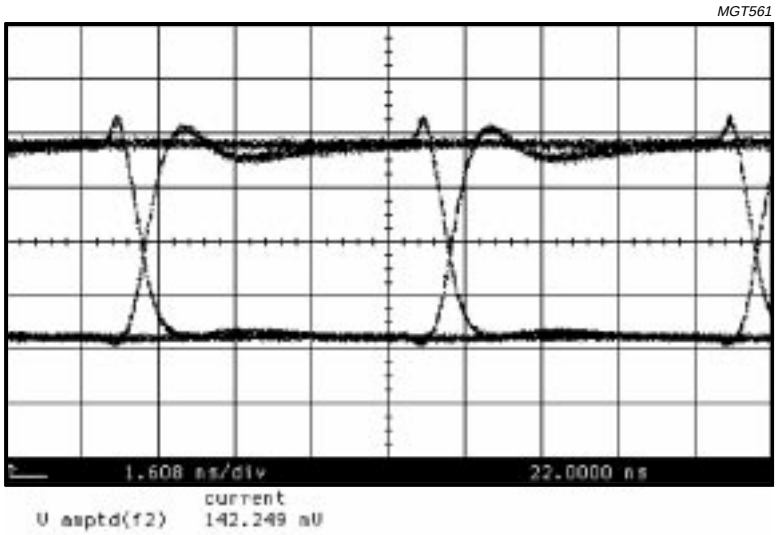


Fig.20 Differential output with −2 dBm optical input power [input current of 1030 μA (p-p)].

BONDING PAD LOCATIONS

SYMBOL	PAD	COORDINATES(1)	
		x	y
DREF	1	95	881
TESTA	2	95	735
GND	3	95	618
GND	4	95	473
IPhoto	5	95	285
TESTB	6	95	147
GND	7	215	95
GND	8	360	95
GND	9	549	95
GND	10	691	95
OUT	11	785	501
OUTQ	12	785	641
V_{CC}	13	567	1055
V_{CC}	14	424	1055
AGC	15	259	1055

Note

1. All coordinates are referenced, in µm, to the bottom left-hand corner of the die.

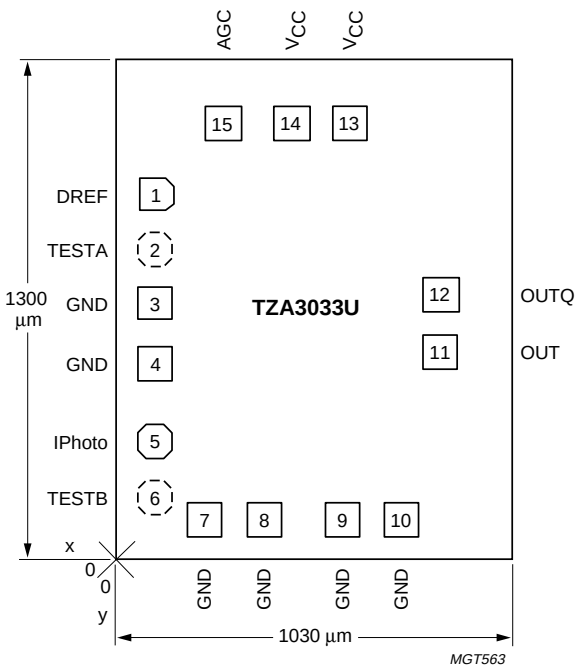


Fig.21 Bonding pad locations of the TZA3033U.

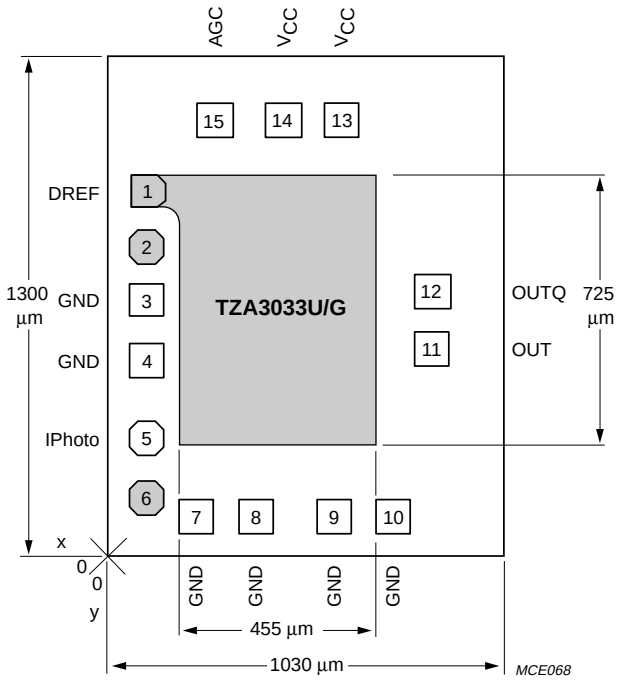


Fig.22 Bonding pad plus gold plate locations of the TZA3033U/G.

Physical characteristics of the bare die

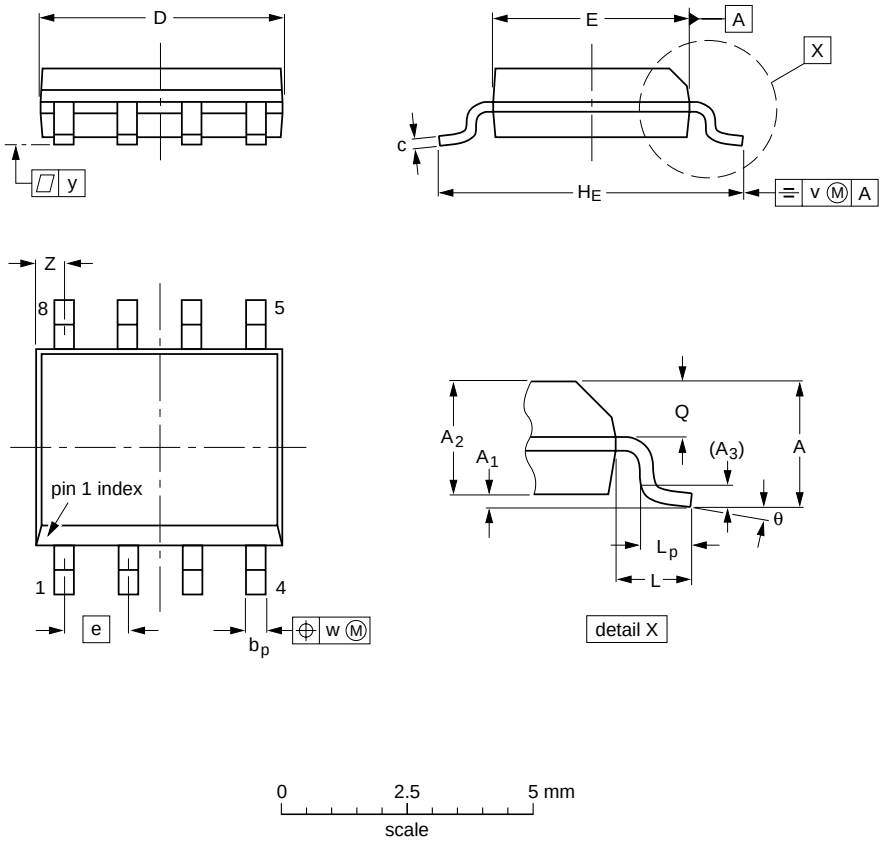
PARAMETER	VALUE
Gold layer(1)	2.8 µm Au + 3.2 µm TiW
Glass passivation	2.1 µm PhosphoSilicate Glass (PSG) on top of 0.65 µm oxynitride
Bonding pad dimension	minimum dimension of exposed metallization is 90 × 90 µm (pad size = 100 × 100 µm)
Metallization	1.22 µm W/AlCu/TiW
Thickness	380 µm nominal
Size	1.03 × 1.30 mm (1.34 mm^2)
Backing	silicon; electrically connected to GND potential through substrate contacts
Attach temperature	<440 °C; recommended die attach is glue
Attach time	<15 s

Note

1. For the TZA3033U/G version only.

PACKAGE OUTLINE

SO8: plastic small outline package; 8 leads; body width 3.9 mm **SOT96-1**



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	$D^{(1)}$	$E^{(2)}$	e	H_E	L	L_p	Q	v	w	y	$Z^{(1)}$	θ
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	5.0 4.8	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8^o 0^o
inches	0.069	0.010 0.004	0.057 0.049	0.01	0.019 0.014	0.0100 0.0075	0.20 0.19	0.16 0.15	0.050	0.244 0.228	0.041	0.039 0.016	0.028 0.024	0.01	0.01	0.004	0.028 0.012	

Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT96-1	076E03	MS-012				~~97-05-22~~ 99-12-27

SOLDERING

Introduction to soldering surface mount packages

This text gives a very brief insight to a complex technology. A more in-depth account of soldering ICs can be found in our *"Data Handbook IC26; Integrated Circuit Packages"* (document order number 9398 652 90011).

There is no soldering method that is ideal for all surface mount IC packages. Wave soldering can still be used for certain surface mount ICs, but it is not suitable for fine pitch SMDs. In these situations reflow soldering is recommended.

Reflow soldering

Reflow soldering requires solder paste (a suspension of fine solder particles, flux and binding agent) to be applied to the printed-circuit board by screen printing, stencilling or pressure-syringe dispensing before package placement.

Several methods exist for reflowing; for example, convection or convection/infrared heating in a conveyor type oven. Throughput times (preheating, soldering and cooling) vary between 100 and 200 seconds depending on heating method.

Typical reflow peak temperatures range from 215 to 250 °C. The top-surface temperature of the packages should preferable be kept below 220 °C for thick/large packages, and below 235 °C for small/thin packages.

Wave soldering

Conventional single wave soldering is not recommended for surface mount devices (SMDs) or printed-circuit boards with a high component density, as solder bridging and non-wetting can present major problems.

To overcome these problems the double-wave soldering method was specifically developed.

If wave soldering is used the following conditions must be observed for optimal results:

- Use a double-wave soldering method comprising a turbulent wave with high upward pressure followed by a smooth laminar wave.
- For packages with leads on two sides and a pitch (e):
  - larger than or equal to 1.27 mm, the footprint longitudinal axis is **preferred** to be parallel to the transport direction of the printed-circuit board;
  - smaller than 1.27 mm, the footprint longitudinal axis **must** be parallel to the transport direction of the printed-circuit board.

  The footprint must incorporate solder thieves at the downstream end.
- For packages with leads on four sides, the footprint must be placed at a 45° angle to the transport direction of the printed-circuit board. The footprint must incorporate solder thieves downstream and at the side corners.

During placement and before soldering, the package must be fixed with a droplet of adhesive. The adhesive can be applied by screen printing, pin transfer or syringe dispensing. The package can be soldered after the adhesive is cured.

Typical dwell time is 4 seconds at 250 °C.
A mildly-activated flux will eliminate the need for removal of corrosive residues in most applications.

Manual soldering

Fix the component by first soldering two diagonally-opposite end leads. Use a low voltage (24 V or less) soldering iron applied to the flat part of the lead. Contact time must be limited to 10 seconds at up to 300 °C.

When using a dedicated tool, all other leads can be soldered in one operation within 2 to 5 seconds between 270 and 320 °C.

Suitability of surface mount IC packages for wave and reflow soldering methods

PACKAGE[1]	SOLDERING METHOD	
	WAVE	REFLOW[2]
BGA, LBGA, LFBGA, SQFP, TFBGA, VFBGA	not suitable	suitable
HBCC, HBGA, HLQFP, HSQFP, HSOP, HTQFP, HTSSOP, HVQFN, HVSON, SMS	not suitable[3]	suitable
PLCC[4], SO, SOJ	suitable	suitable
LQFP, QFP, TQFP	not recommended[4][5]	suitable
SSOP, TSSOP, VSO	not recommended[6]	suitable

Notes

1. For more detailed information on the BGA packages refer to the *"(LF)BGA Application Note*" (AN01026); order a copy from your Philips Semiconductors sales office.
2. All surface mount (SMD) packages are moisture sensitive. Depending upon the moisture content, the maximum temperature (with respect to time) and body size of the package, there is a risk that internal or external package cracks may occur due to vaporization of the moisture in them (the so called popcorn effect). For details, refer to the Drypack information in the *"Data Handbook IC26; Integrated Circuit Packages; Section: Packing Methods"*.
3. These packages are not suitable for wave soldering. On versions with the heatsink on the bottom side, the solder cannot penetrate between the printed-circuit board and the heatsink. On versions with the heatsink on the top side, the solder might be deposited on the heatsink surface.
4. If wave soldering is considered, then the package must be placed at a 45° angle to the solder wave direction. The package footprint must incorporate solder thieves downstream and at the side corners.
5. Wave soldering is suitable for LQFP, TQFP and QFP packages with a pitch (e) larger than 0.8 mm; it is definitely not suitable for packages with a pitch (e) equal to or smaller than 0.65 mm.
6. Wave soldering is suitable for SSOP and TSSOP packages with a pitch (e) equal to or larger than 0.65 mm; it is definitely not suitable for packages with a pitch (e) equal to or smaller than 0.5 mm.

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